

/ Descriptions

MM 3 5 1

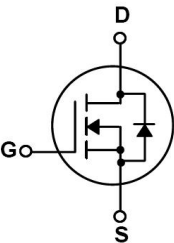
/ Features

1 3 / 1 1 3 5 1 3

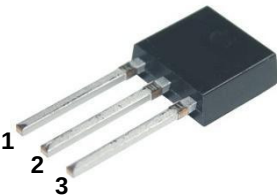
/ Applications

1 3 1 3 GF2GF 1 3 5 1

/ Equivalent Circuit



/ Pinning

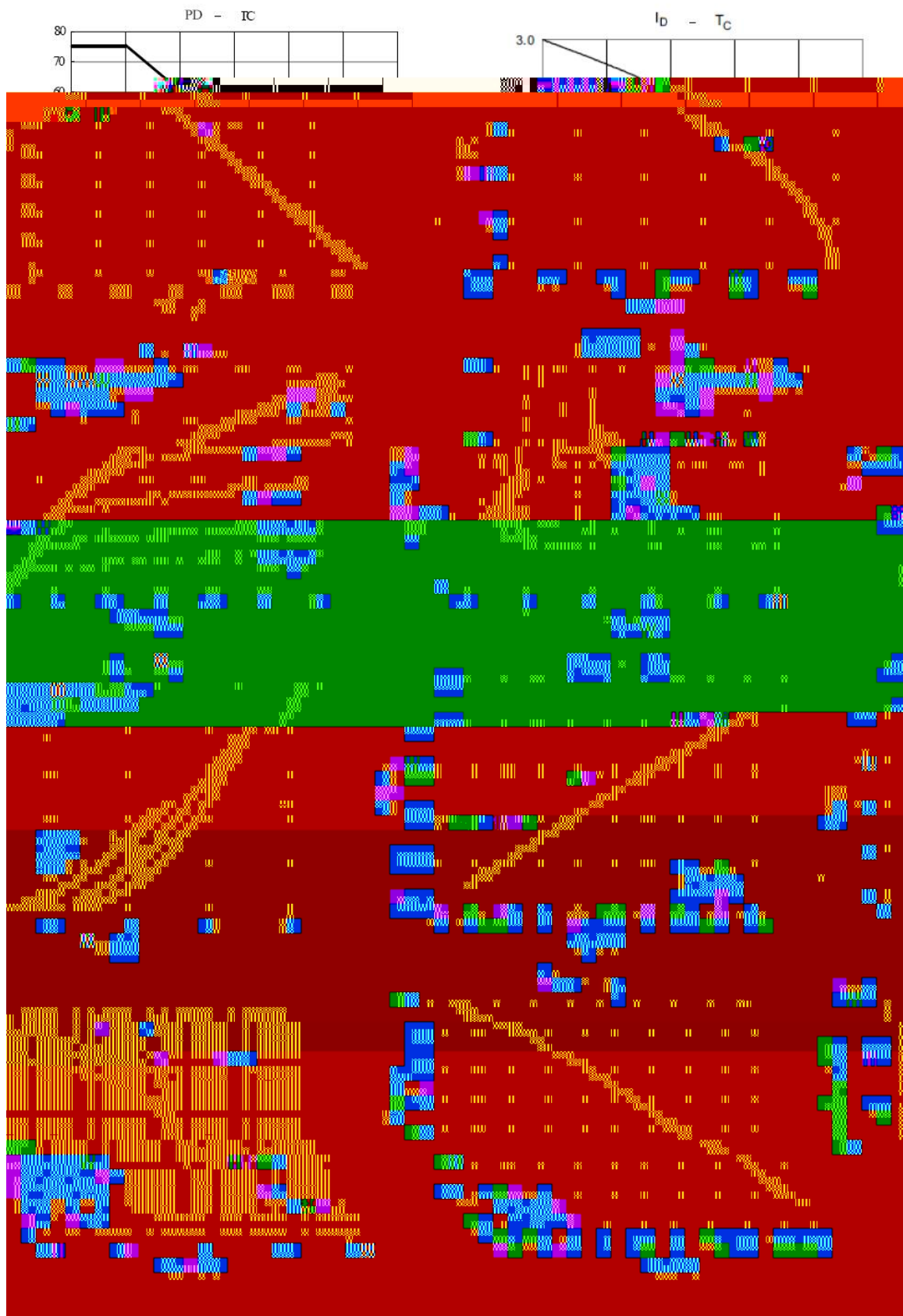


X X X

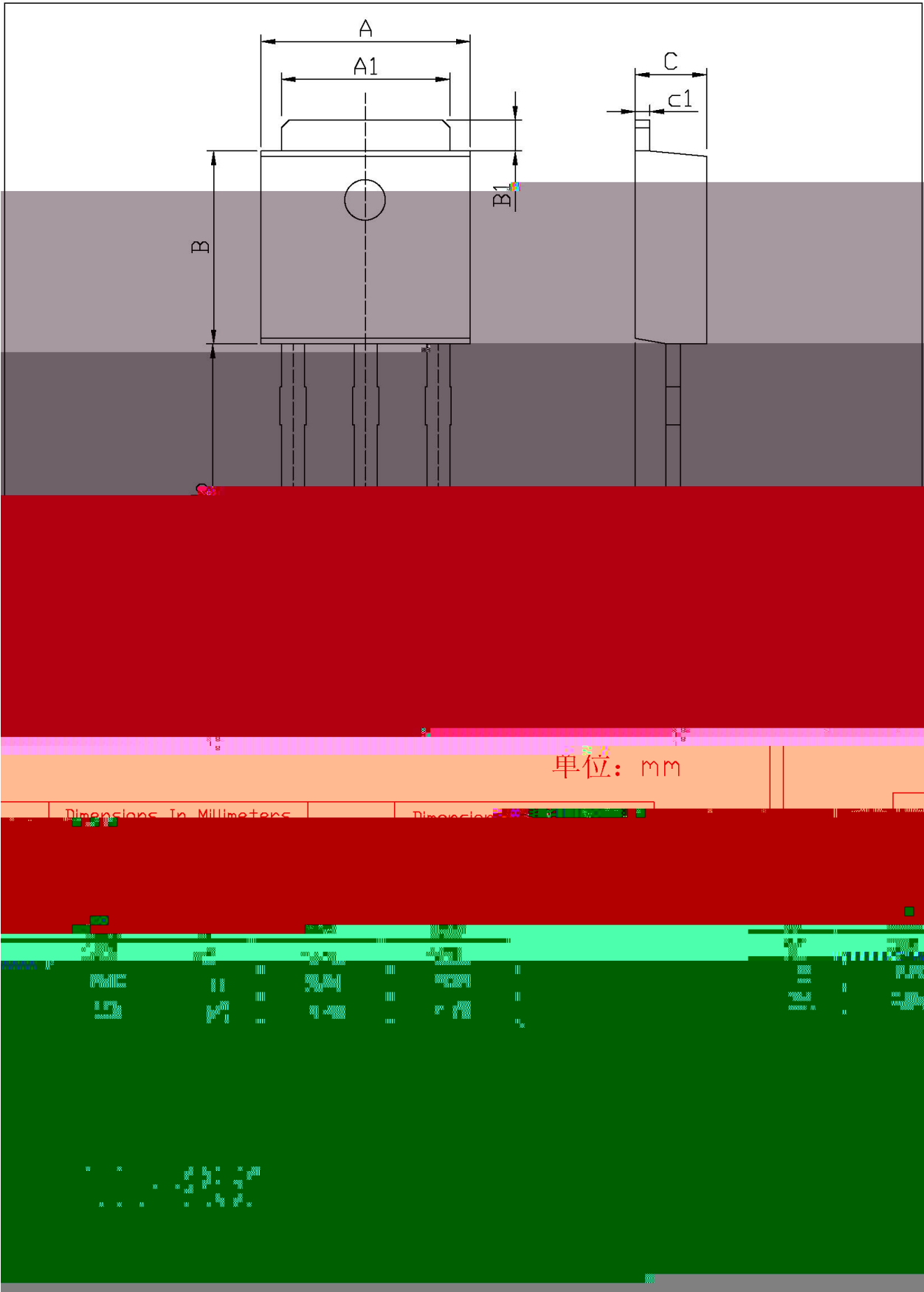
/ hFE Classifications & Marking

M 1 3

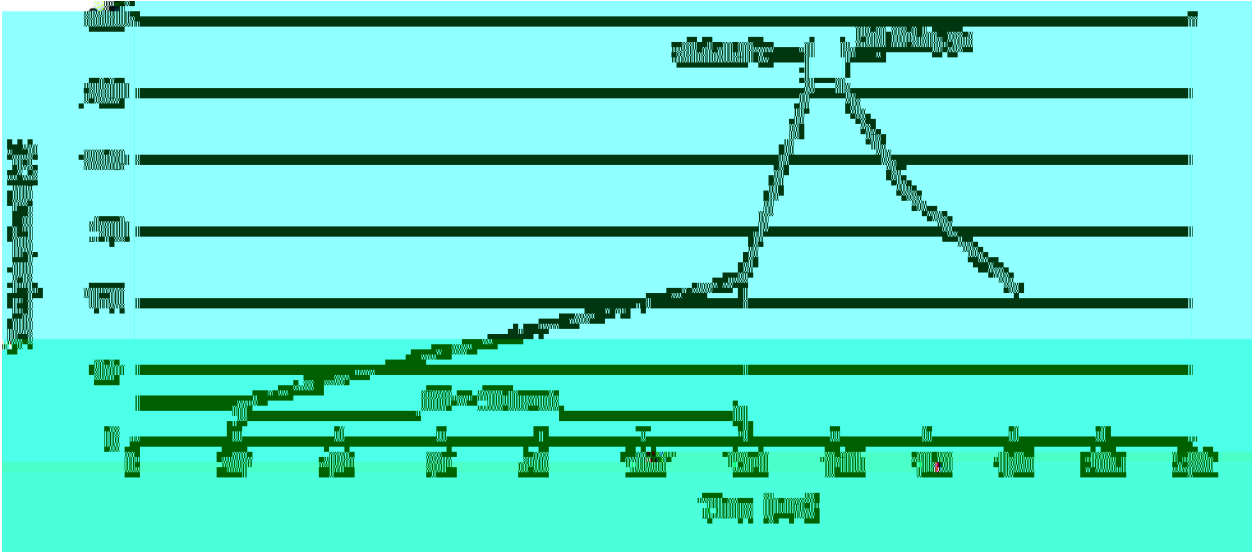
/ Electrical Characteristic Curve



/ Package Dimensions



() / Temperature Profile for Dip Soldering(Pb-Free)



“X
□ŷ Ķ † i`H Ķ †
ŠÖ□ŷ ° † i`H `Y/ħ ° ° † °
i`ŷ, o ŷħ Ķ † †

/ Resistance to Soldering Heat Test Conditions

□ŷχ ° † `H χ °

/ Packaging SPEC.

“Q T Y

封装形式	包装数量					包装尺寸 :		
	只 袋	袋 盒	只 盒	盒 箱	只 箱	袋	盒	箱

„ 1 Y

封装形式	包装数量					包装尺寸 :		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices